

Filing Date: September 21, 2001

Title: COPPER-CONTAINING C4 BALL-LIMITING METALLURGY STACK FOR ENHANCED RELIABILITY OF PACKAGED STRUCTURES AND METHOD OF MAKING SAME

Å to about 4,000 Å, and wherein the metal third layer has a thickness in a range from about 1,000 Å to about 5,000 Å.

38. (New) The system according to claim 23, wherein the metal third layer includes a NiV composition over the metal second layer, wherein the NiV composition has a thickness in a range from about 1,000 Å to about 5,000 Å, and wherein the metal second layer has a thickness in a range from about 1,000 Å to about 5,000 Å.

39. (New) The system according to claim 23, wherein the metal third layer includes a copper stud over the metal second layer, wherein the copper stud has a thickness in a range from about 5 micrometers to about 15 micrometers, and wherein the metal second layer has a thickness in a range from about 1,000 Å to about 5,000 Å.

REMARKS

Applicant respectfully asserts that the claims are now in condition for examination. No new matter was added by the presentation of new claims 29-39. Support for new claim 29 comes from claim 19 and throughout the specification. Support for new claim 30 comes from claim 20 and throughout the specification. Support for new claim 31 comes from claim 20 and throughout the specification. Support for new claim 32 comes from claim 21 and throughout the specification. Support for new claim 33 comes from claim 21 and throughout the specification. Support for new claim 34 comes from claim 22 and throughout the specification. Support for new claim 35 comes from claim 22 and throughout the specification. Support for new claim 36 comes from claim 19 and throughout the specification. Support for new claim 37 comes from claim 20 and throughout the specification. Support for new claim 38 comes from claim 21 and throughout the specification. Support for new claim 39 comes from claim 22 and throughout the specification.

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The Examiner is invited to contact Applicants' Representative John Greaves at 801/278-9171 or the below signed attorney if there are any questions regarding this Response or if prosecution of this application may be assisted thereby.

If necessary, please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

Respectfully submitted,

MADHAV DATTA ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
P.O. Box 2938
Minneapolis, MN 55402
(612) 349-9592

Date Oct. 3, 2002

By Ann M. McCrackin

Ann M. McCrackin

Reg. No. 42,858

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner of Patents, Washington, D.C. 20231, on this 3 day of October, 2002.

Jane E. Brockschink
Name

Jane Brockschink
Signature